

Electronic Supporting Information

Self-aligned High Resolution Patterning Process for Large Area Printed Electronics

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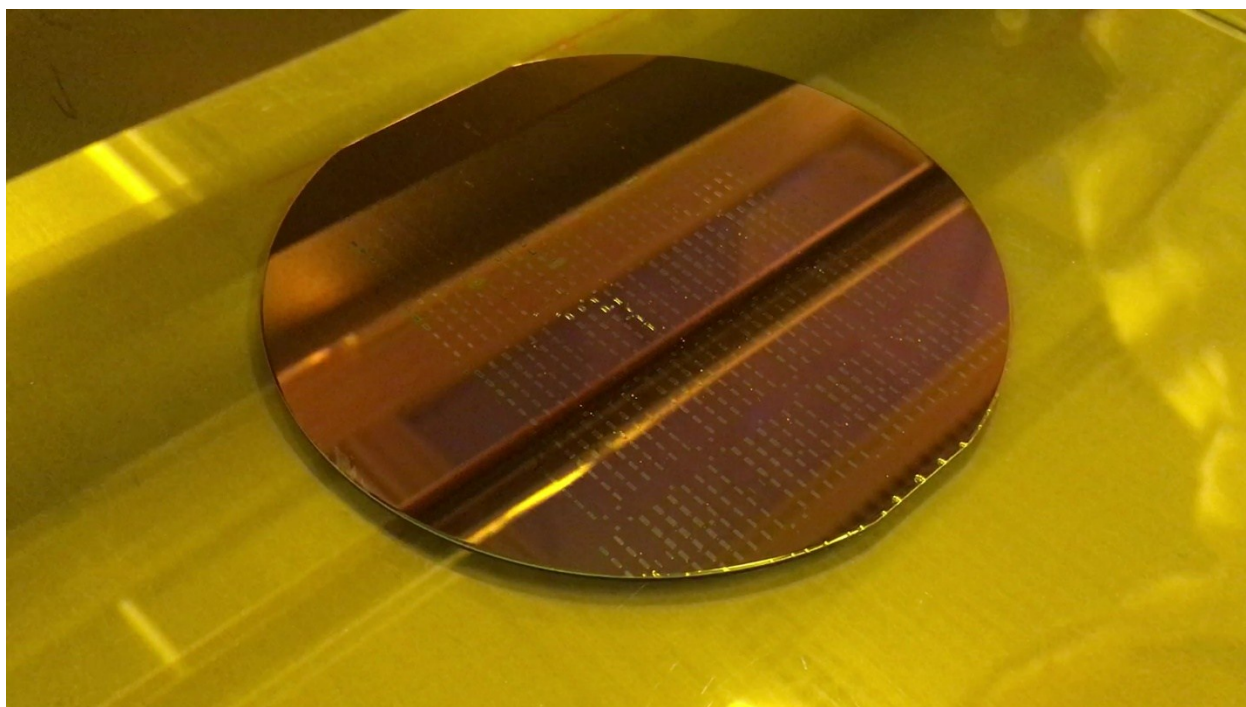


Figure S1. Movie clip of self-align printing process

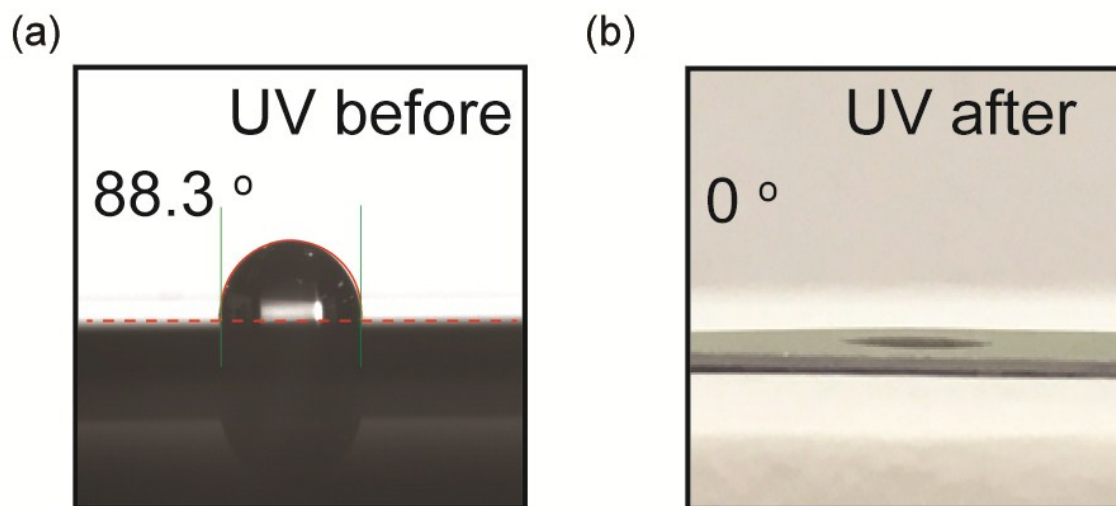


Figure S2. CCD image of the surface as deposited: (a) SAM, and (b) after UV treatment of the substrate.

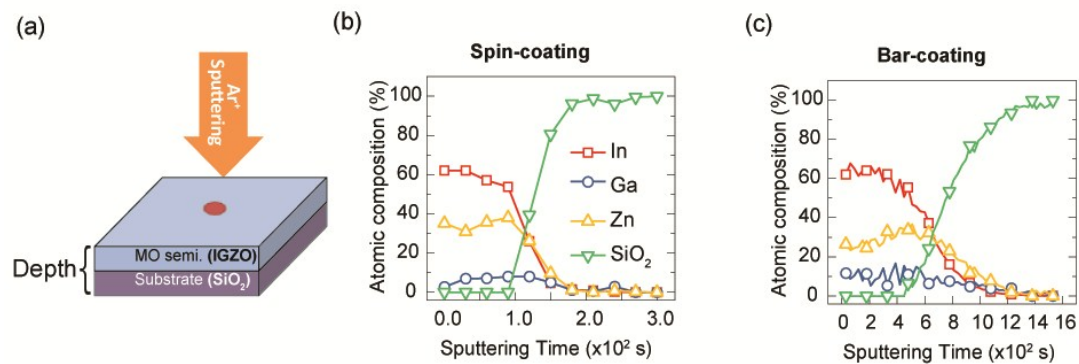


Figure S3. XPS for atomic concentration analysis at (a) spot of the IGZO film. (b) and (c) depth profiles of the spin-coated and bar-coated film.

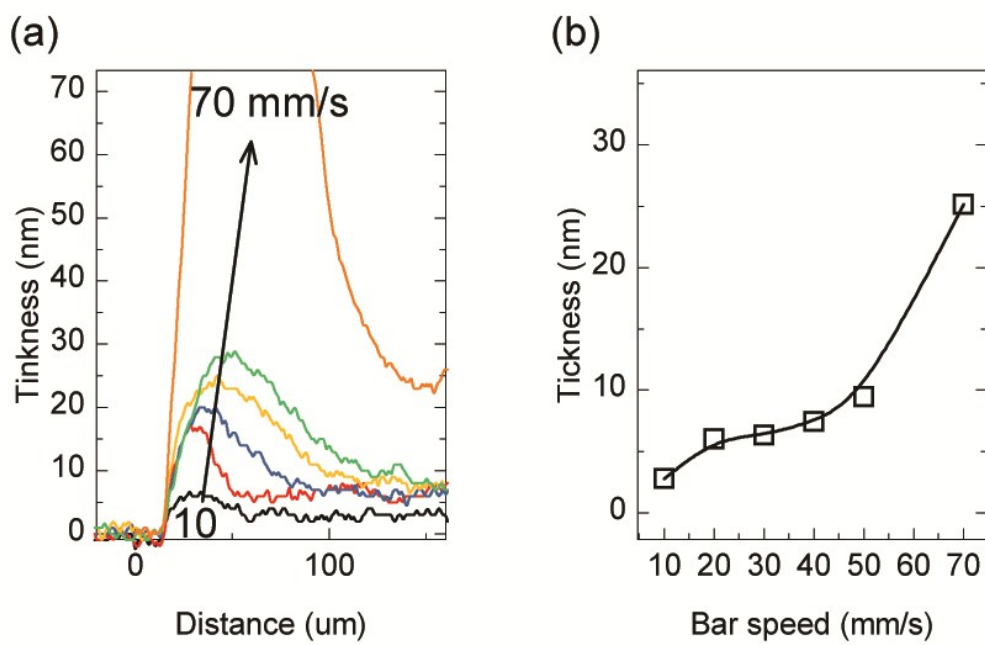


Figure S4. Bar-coated oxide film thickness at different speeds (from 10 to 70 mm/s).